

1 Characteristics

Table 1. Compliant with the following standards

STANDARD	Peak surge voltage (V)	Waveform voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μ s 10/1000 μ s	500 100	2/10 μ s 10/1000 μ s	20 24
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	40
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0
ITU-T-K20/K21	6000 1500	10/700 μ s	150 37.5	5/310 μ s	110 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
VDE0433	4000 2000	10/700 μ s	100 50	5/310 μ s	60 10
VDE0878	4000 2000	1.2/50 μ s	100 50	1/20 μ s	18 0
IEC61000-4-5	4000 4000	10/700 μ s 1.2/50 μ s	100 100	5/310 μ s 8/20 μ s	60 18
FCC Part 68, lightning surge type A	1500 800	10/160 μ s 10/560 μ s	200 100	10/160 μ s 10/560 μ s	26 15
FCC Part 68, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0

Table 2. Absolute ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter		Value	Unit
I_{PP}	Repetitive peak pulse current	10/1000 μs	30	A
		8/20 μs	70	
		10/560 μs	35	
		5/310 μs	40	
		10/160 μs	45	
		1/20 μs	70	
		2/10 μs	100	
I_{FS}	Fail-safe mode : maximum current ⁽¹⁾	8/20 μs	2.5	kA
I_{TSM}	Non repetitive surge peak on-state current (sinusoidal)	t = 0.2 s	14	A
		t = 1 s	10.5	
		t = 2 s	9	
		t = 15 mn	3	
I^2t	I^2t value for using	t = 16.6 ms	5.7	A^2s
		t = 20 ms	4.9	
T_{stg}	Storage temperature range		-55 to + 150	$^{\circ}\text{C}$
T_j	Maximum junction temperature		150	$^{\circ}\text{C}$
T_L	Maximum lead temperature for soldering during 10 s.		260	$^{\circ}\text{C}$

1. In fail safe mode, the device acts as a short circuit.

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient (with recommended footprint)	120	$^{\circ}\text{C/W}$
$R_{th(j-l)}$	Junction to leads	30	$^{\circ}\text{C/W}$

Table 4. Electrical characteristics - definitions ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

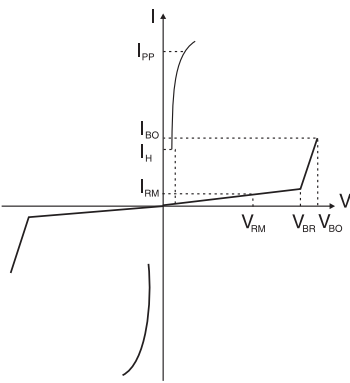
Symbol	Parameter	
V_{RM}	Stand-off voltage	
V_{BR}	Breakdown voltage	
V_{BO}	Breakover voltage	
I_{RM}	Leakage current	
I_{PP}	Peak pulse current	
I_{BO}	Breakover current	
I_H	Holding current	
V_R	Continuous reverse voltage	
I_R	Leakage current at V_R	
C	Capacitance	

Table 5. Electrical characteristics - values ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Types	$I_{RM} @ V_{RM}$		$I_R^{(1)} @ V_R$		Dynamic V_{BO}	Static $V_{BO} @ I_{BO}$		I_H	$C^{(2)}$	$C^{(3)}$
	max.		max.		max.	max.	max.	min.	typ.	typ.
	μA	V	μA	V	V	V	mA	mA	pF	pF
SMP30-62	2	56	5	62	85	82	800	150	20	40
SMP30-68		61		68	93	90			20	40
SMP30-100		90		100	135	133			16	35
SMP30-120		108		120	160	160			16	30
SMP30-130		117		130	173	173			14	30
SMP30-180		162		180	235	240			12	25
SMP30-200		180		200	262	267			12	25
SMP30-220		198		220	285	293			10	20
SMP30-240		216		240	300	320			10	20
SMP30-270		243		270	350	360			10	20

1. I_R measured at V_R guarantee $V_{BR\text{ min}} \geq V_R$ 2. $V_R = 50\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$ 3. $V_R = 2\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$

Figure 2. Pulse waveform

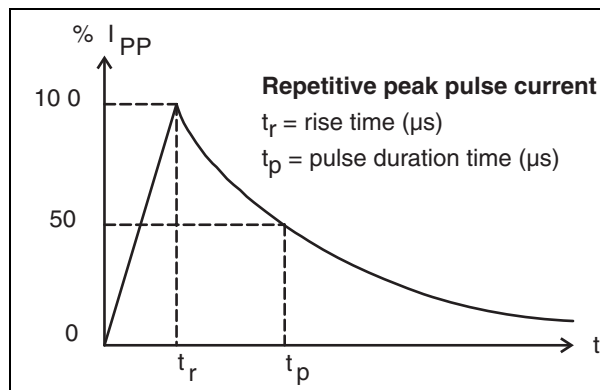


Figure 3. Non repetitive surge peak on-state current versus overload duration

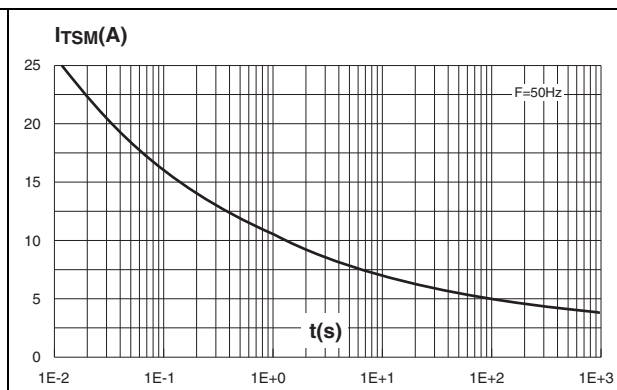


Figure 4. On-state voltage versus on-state current (typical values)

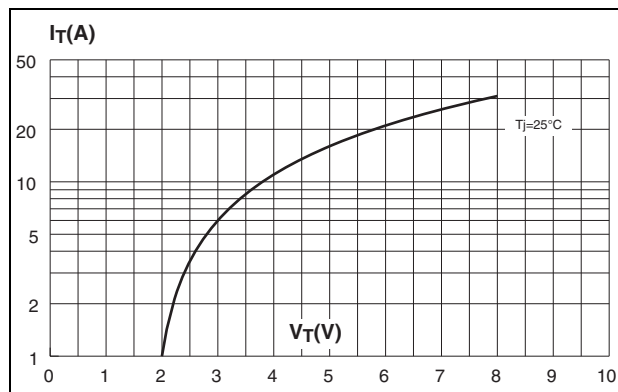


Figure 5. Relative variation of holding current versus junction temperature

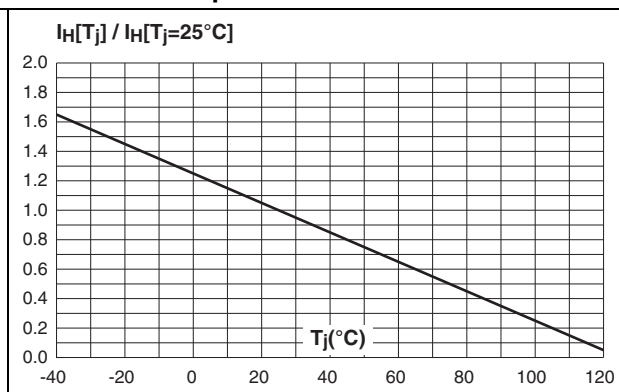


Figure 6. Relative variation of breakover voltage versus junction temperature

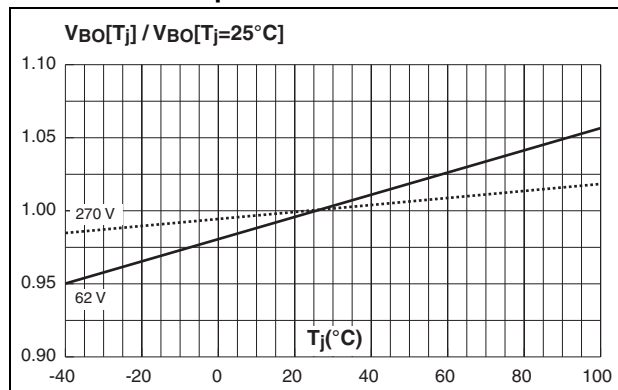


Figure 7. Relative variation of leakage current versus reverse voltage applied (typical values)

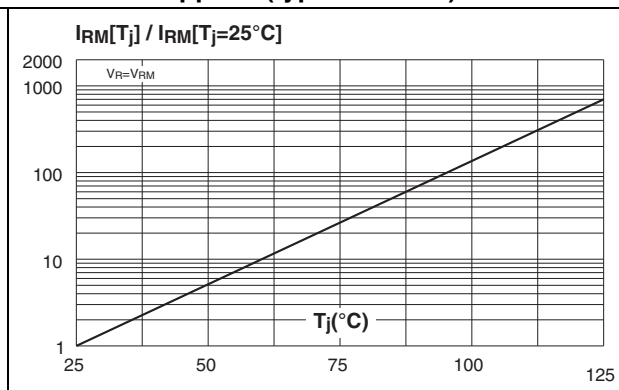


Figure 8. Variation of thermal impedance junction to ambient versus pulse duration

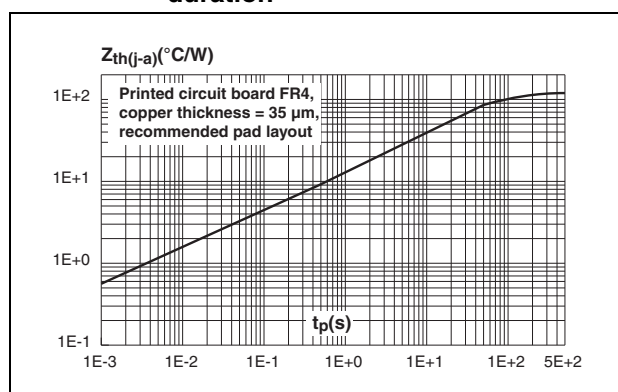
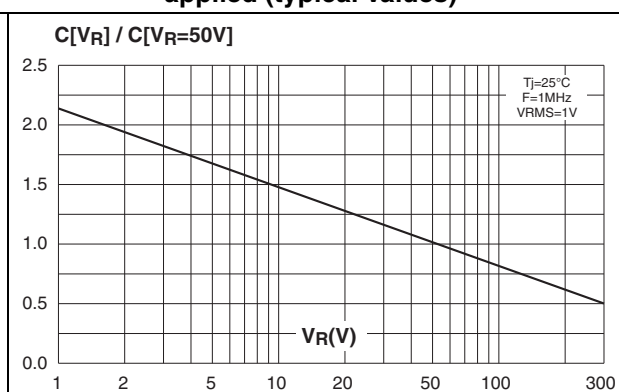
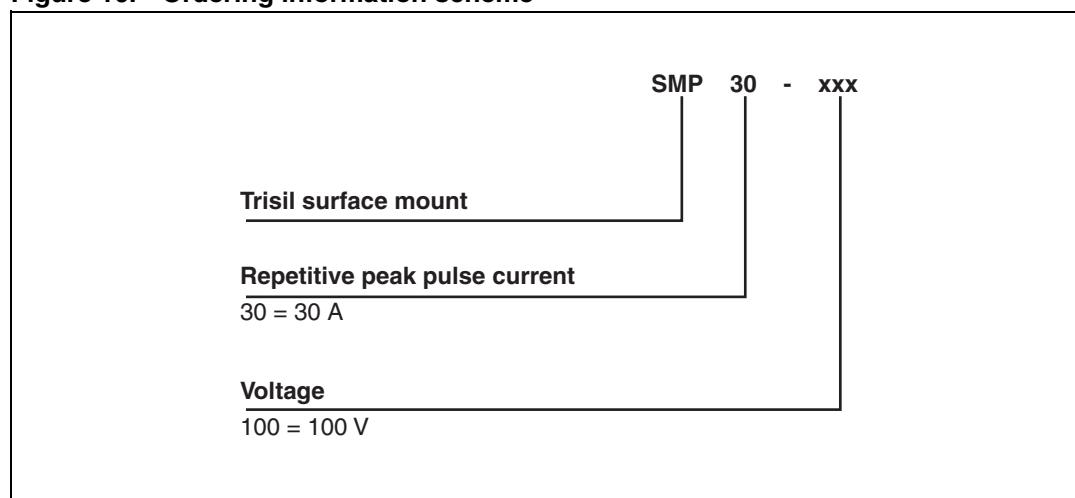


Figure 9. Relative variation of junction capacitance versus reverse voltage applied (typical values)



2 Ordering information scheme

Figure 10. Ordering information scheme



3 Package mechanical data

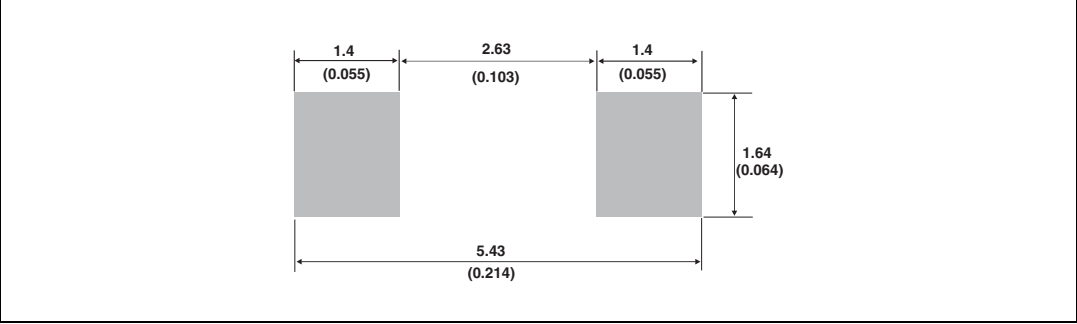
- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 6. SMA dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

Figure 11. Footprint (dimensions in mm)



4 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
SMP30-62	QAA	SMA	0.06 g	5000	Tape and reel
SMP30-68	QAB				
SMP30-100	QAC				
SMP30-120	QAD				
SMP30-130	QAE				
SMP30-180	QAF				
SMP30-200	QAG				
SMP30-220	QAH				
SMP30-240	QAI				
SMP30-270	QAJ				

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
November-2002	4B	Last update.
10-Nov-2004	5	SMA package dimensions update. Reference A1 max. changed from 2.70mm (0.106 inch) to 2.03mm (0.080 inch).
13-Dec-2004	6	Figure 7 text legend corrected from "... reverse voltage applied" to "... junction capacitance".
01-Jul-2010	7	Added ECOPACK statement. Updated trademark statement. Removed section on test circuits.

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

